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**METHOD AND SYSTEM FOR DETERMINING A PERFORMANCE OF PLASMA
ETCH EQUIPMENT**

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Abstract of the Disclosure

A method of determining a performance of plasma etch
equipment is provided. The method comprises extracting
10 data that depend on the performance of plasma etch equip-
ment, during etching of the wafer, for example by calcu-
lating an etch rate and by calculating a non-uniformity
of a film being etched. After that, the extracted data
are compared to predetermined data, and on the basis of a
15 result of comparing the extracted data with predetermined
data the performance of the plasma etch equipment is de-
termined. Further, a system for determining a performance
of plasma etch equipment is provided.

20 (Figure 1)